



Material Content Data Sheet



Sales Product Name	IPN10EL-S			Issued		27. September 2017		
MA#	MA001056682							
Package	PG-SSOP-14-5			Weight*		82.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.056	1.28	1.28	12770	12770
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		417	
	non noble metal	iron	7439-89-6	0.689	0.83		8332	
	non noble metal	copper	7440-50-8	27.978	33.83	34.71	338295	347148
wire	non noble metal	copper	7440-50-8	0.079	0.10	0.10	958	958
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1226	
	plastics	epoxy resin	-	4.664	5.64		56396	
	inorganic material	silicondioxide	60676-86-0	45.931	55.53	61.29	555373	612995
leadfinish	non noble metal	tin	7440-31-5	0.988	1.20	1.20	11950	11950
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9282	9282
glue	plastics	epoxy resin	-	0.101	0.12		1224	
	noble metal	silver	7440-22-4	0.304	0.37	0.49	3673	4897
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com